

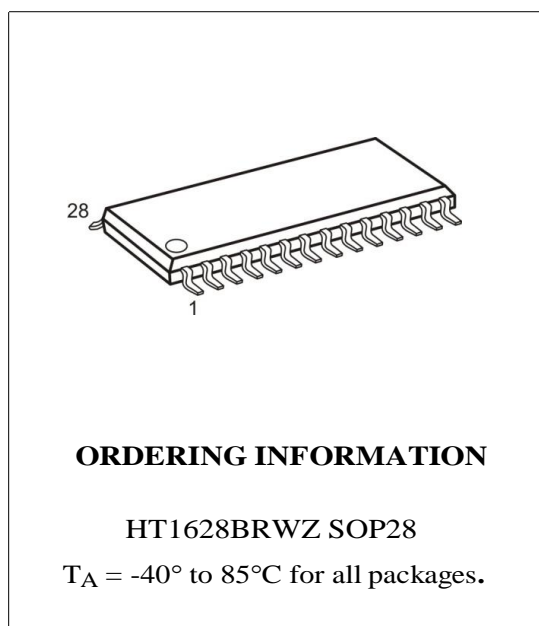
## ***Low voltage version LED display driver chip***

### **GENERAL DESCRIPTION**

The HT1628 is a common cathode type LED panel display driver with output size -4 digits x13 segments or 7 digits x 10 segments and addition key scan function. Serial interface provide connection with microprocessor.

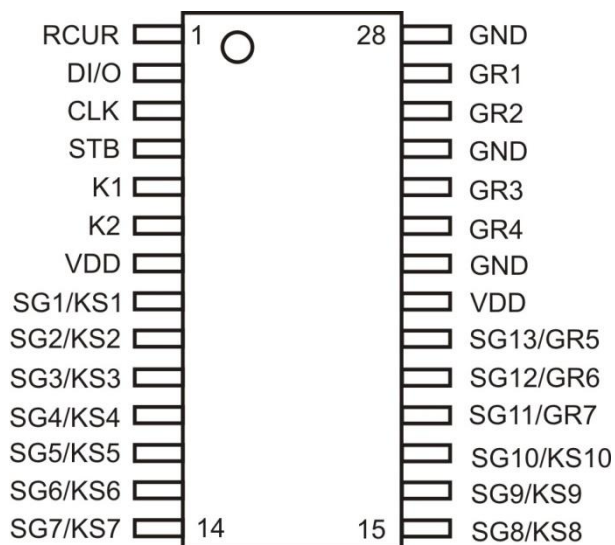
### **FEATURES**

- ◆ Wide operation Voltage: 3.3V
- ◆ Serial Interface
- ◆ 8-Step Dimming Circuitry
- ◆ Built in OSC generator  
(with external resistor regulation)
- ◆ Pulse Segment Current: 10 mA type  
@  $V_{DD} = 3.3V$
- ◆ Key scanning:  $10 \times 2$  matrix
- ◆ Operation Temperature:  $-40$  to  $85^{\circ}C$
- ◆ PKG option

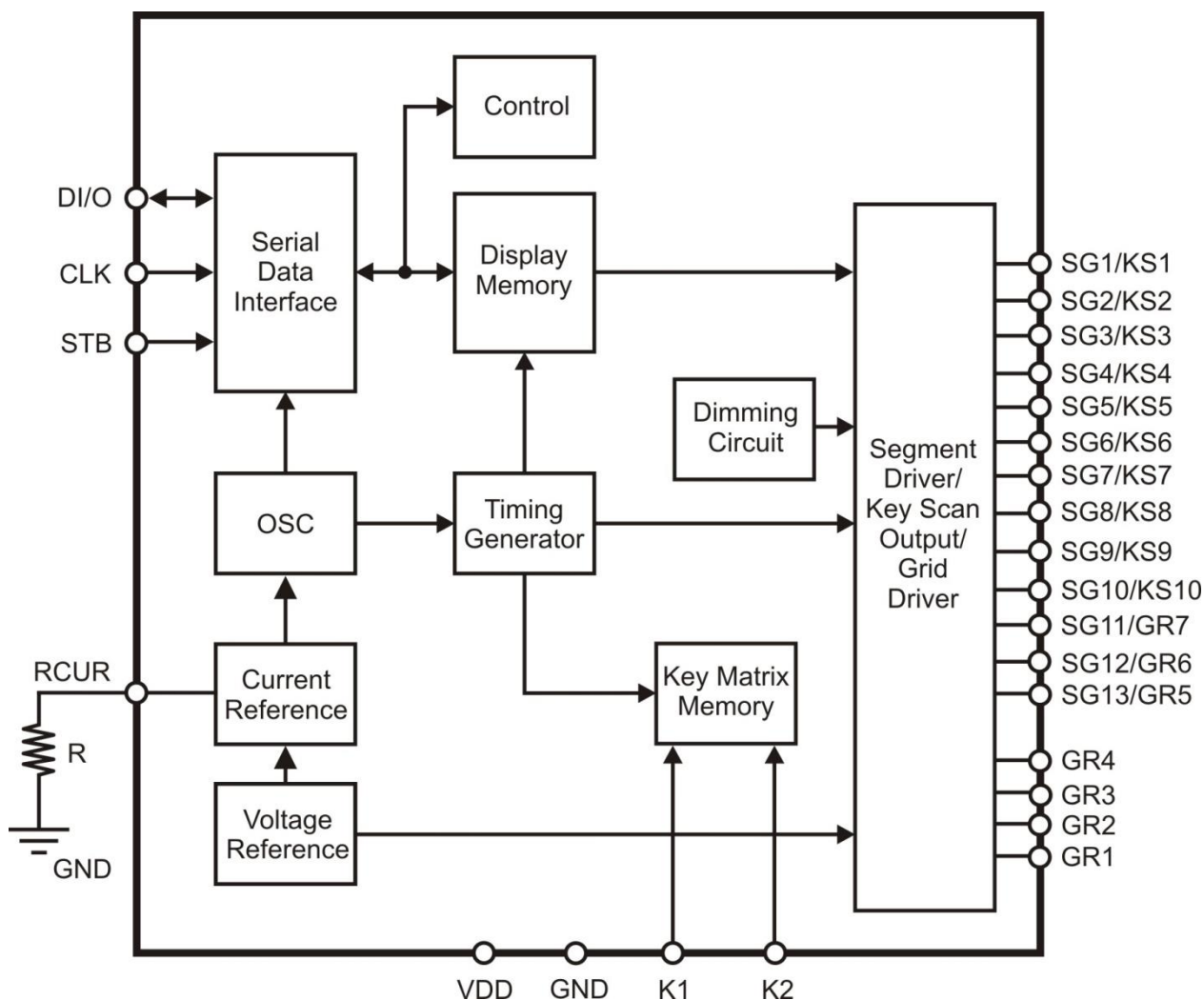


### **APPLICATIONS**

- ◆ Micro-computer Peripheral Device
- ◆ VCR set
- ◆ DVD Combo set
- ◆ DMB Player

**PIN ASSIGNMENT**

**PIN LIST AND DESCRIPTIONS**

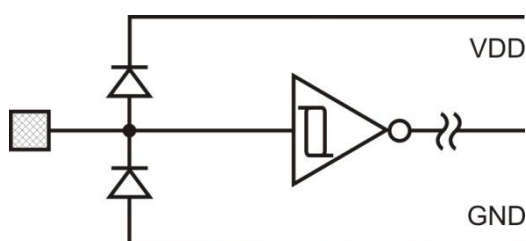
Pin Name	I/O	Description	Pin №
RCUR	I	A resistor is connected to this pin to determine the SG1-SG13 output current and internal oscillation frequency.	1
DI/O	I/O	Data Input - Output Pin This pin inputs serial data at the rising edge of the clock (starting from the bit). Data Output Pin - N-Channel, Open-Drain This pin outputs serial data at the falling edge of the clock.	2
CLK	I	Clock Input Pin This pin reads serial data at the rising edge and output data at the falling edge.	3
STB	I	Serial Interface Strobe Pin The data input after the STB has fallen is processed. When this pin is HIGH, CLK is ignored.	4
K1, K2	I	Key Data Input Pins The data sent to these pins are latched at the end of the display cycle. (Internal Pull-Low Resistor).	5, 6
VDD	-	Power Supply	7, 21
SG1/KS1 to SG10/KS10	O	Segment Output Pins (P-Channel, Open Drain) Also acts as the Key Source.	8 - 17
SG11/GR7 to SG13/GR5	O	Segment / Grid Output Pins	18 - 20
GND	-	Ground Pins	22, 25, 28
GR4 to GR1	O	Grid Output Pins	23, 24, 26, 27



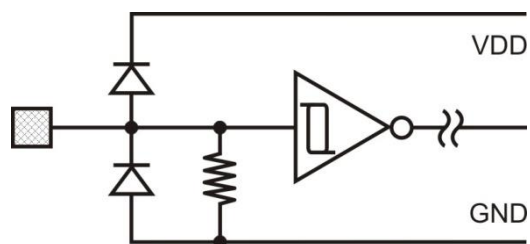
### Figure. Block Diagram

The schematic diagrams of the input and output circuits are shown below.

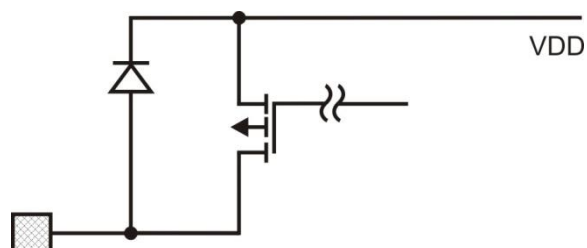
**Input Pins: CLK, STB & DIN(DI/O)**



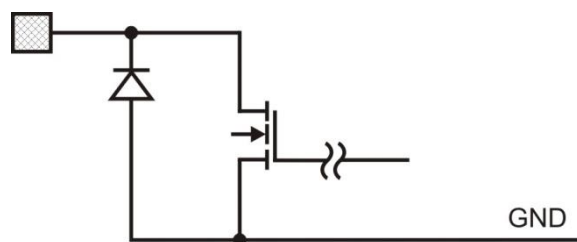
**Input Pins: K1, K2**



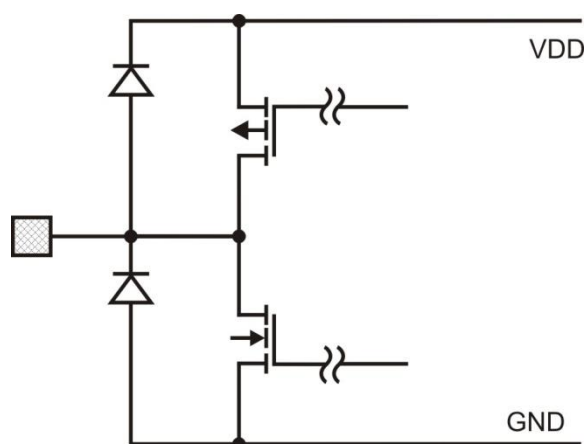
**Input Pins: RCUR, SG1 to SG10**



**Output Pins: DOUT(DI/O), GR1 to GR4**



**Output Pins: SG11/GR7, SG12/GR6 & SG13/GR5**



## FUNCTIONAL DESCRIPTION

### Commands

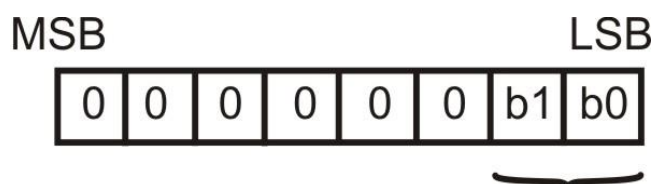
A command is the first byte (b0 to b7) inputted to HT1628 via DI/O Pin after STB pin has changed from "HIGH" to "LOW" state. If for some reason the STB Pin is set "HIGH" while data or commands are being transmitted, the serial communication is initialized, and the data/commands being transmitted are considered invalid.

### COMMAND 1: DISPLAY MODE SETTING COMMANDS

HT1628 provides 4 display modes setting as shown in the diagram below: As stated earlier a command is the first one byte (b0 to b7) transmitted to HT1628 via the DIN, DI/O Pin when STB is "LOW". However, for these commands, Bit 3 & Bit 8 (b2 to b7) are given a value of "0".

The Display Mode Setting Commands determine the number of segments and grids be used (4 grids to 13 segments, 7 grids to 10 segments). A display command "ON" must be executed in order to resume display. If the same mode setting is selected, no command execution is take place, therefore, nothing happens.

When Power is turned "ON", the mode 11 is selected.



Display Mode Settings:

- 00: 4 Grids, (13 Segments)
- 01: 5 Grids, (12 Segments)
- 10: 6 Grids, (11 Segments)
- 11: 7 Grids, (10 Segments)

### COMMAND 2: DATA SETTING COMMANDS

The Data Setting Commands executes the Data Write Mode for HT1628. The Data Setting Command, the bits5 and 6 (b4, b5) are given the value of "0". , bit7 (b6) is given the value of "1" while bit8 (b7) is given the value of "0". Please refer to the diagram below. When power is turned ON, bit 4 to bit 1 (b3 to b0) are given the value of "0".



Please refer to the diagram below.



## Display Mode and RAM Address

Data transmitted from an external device to HT1628 via the serial interface are stored in the Display RAM and are assigned addresses. The RAM Addresses of HT1628 are given below in 8 bit unit.

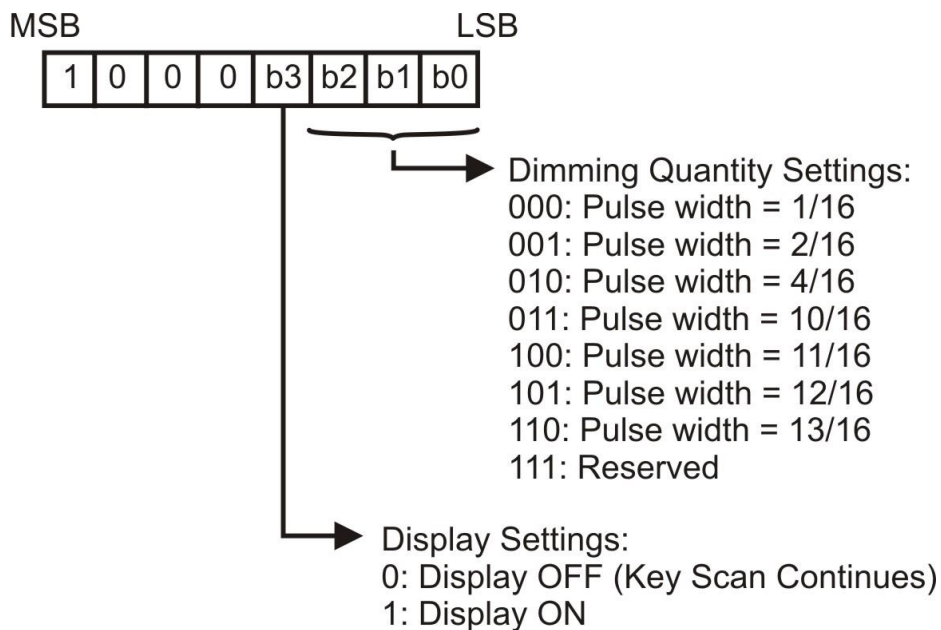
SG1	SG4	SG5	SG8	SG9	SG12	SG13	
00HL	00HU		01HL	01HU			DIG1
02HL	02HU		03HL	03HU			DIG2
04HL	04HU		05HL	05HU			DIG3
06HL	06HU		07HL	07HU			DIG4
08HL	07HU		09HL	09HU			DIG5
0AHL	0AHU		0BHL	0BHU			DIG6
0CHL	0CHU		0DHL	0DHU			DIG7

b0	b3	b4	b7
xxHL		xxHU	
Lower 4 bits		Higher 4 bits	

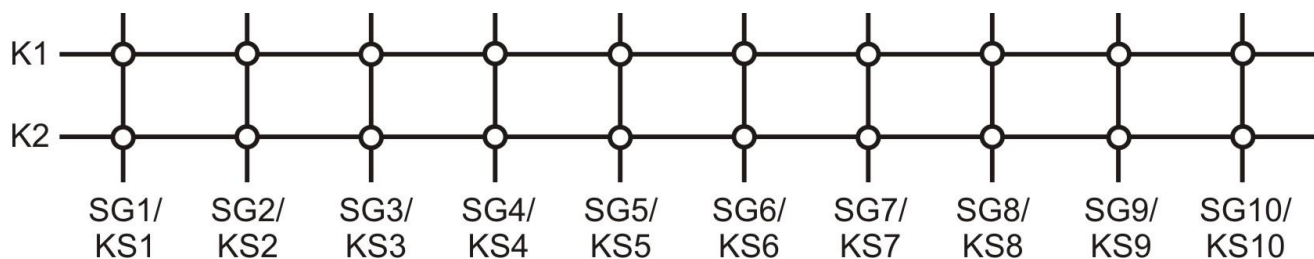
## COMMAND 4: DISPLAY CONTROL COMMANDS

The Display Control Commands are used to turn ON or OFF a display. It also used to set the pulse width. Please refer to the diagram below. When the power is turned ON, a 1/16 pulse width is selected and the displayed is turned OFF.

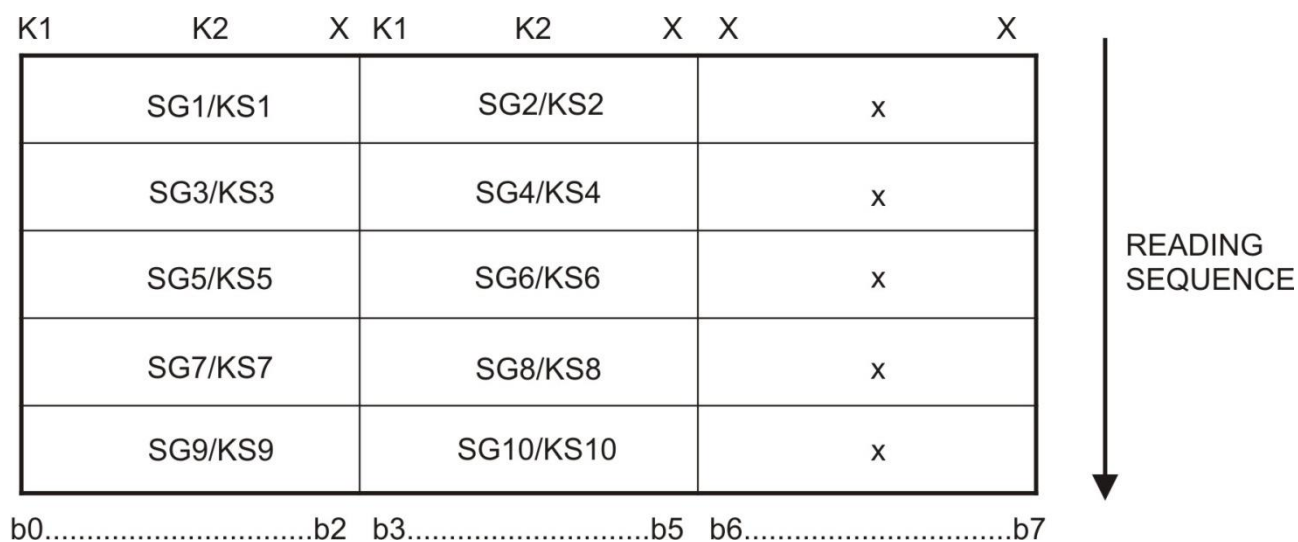


## KEY MATRIX & KEY INPUT DATA STOREGE RAM

Key Matrix consists of 10 x 2 arrays as shown below:

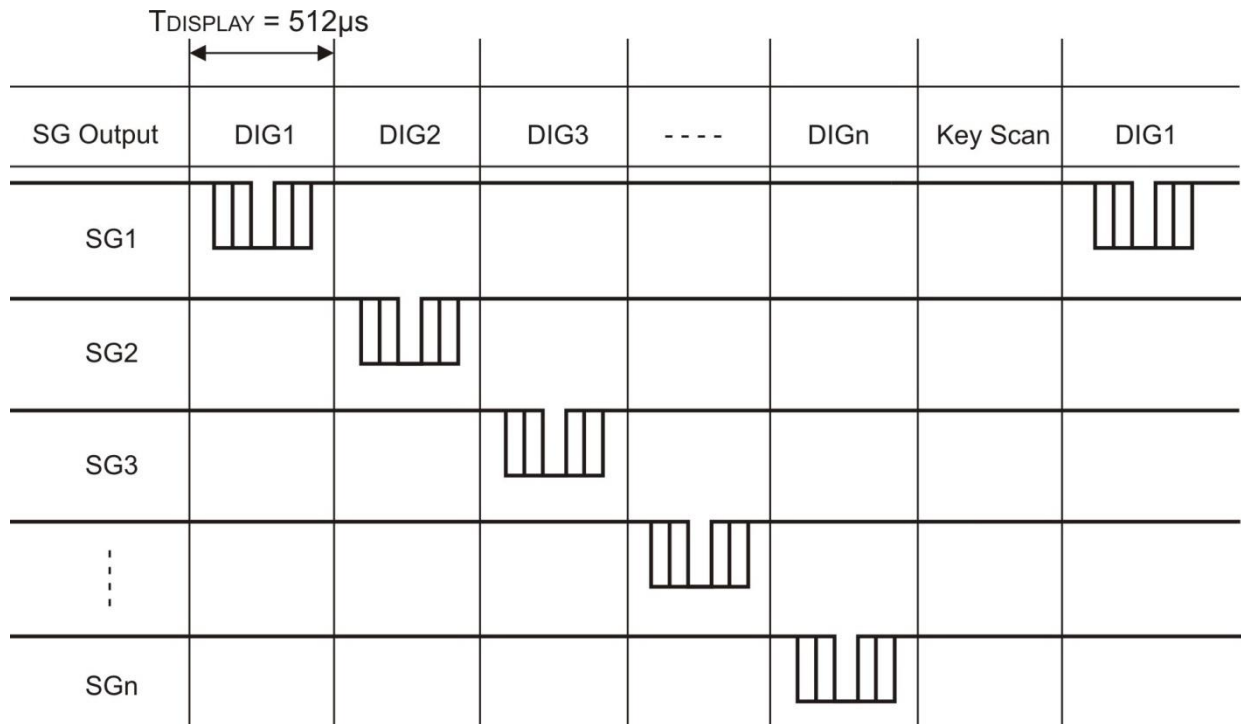


Each data entered by each key (or any combination of keys) is stored as follows and read by a READ Command, starting from the last significant bit. When the most significant bit of the data (b0) has been read, the least significant bit of the next data (b7) is read.



Note: b2, b5, b6 and b7 do not care.

## SCANNING AND DISPLAY TIMING

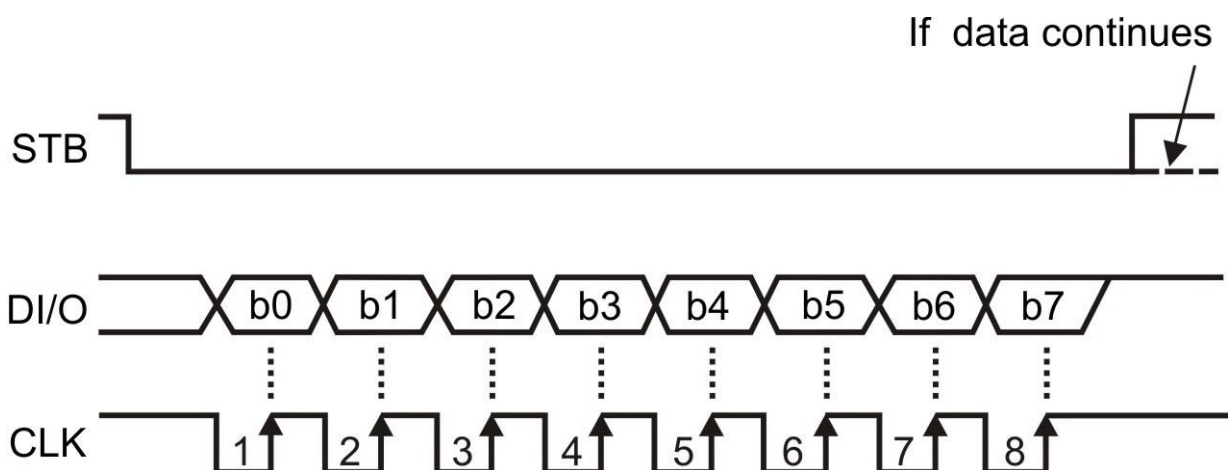


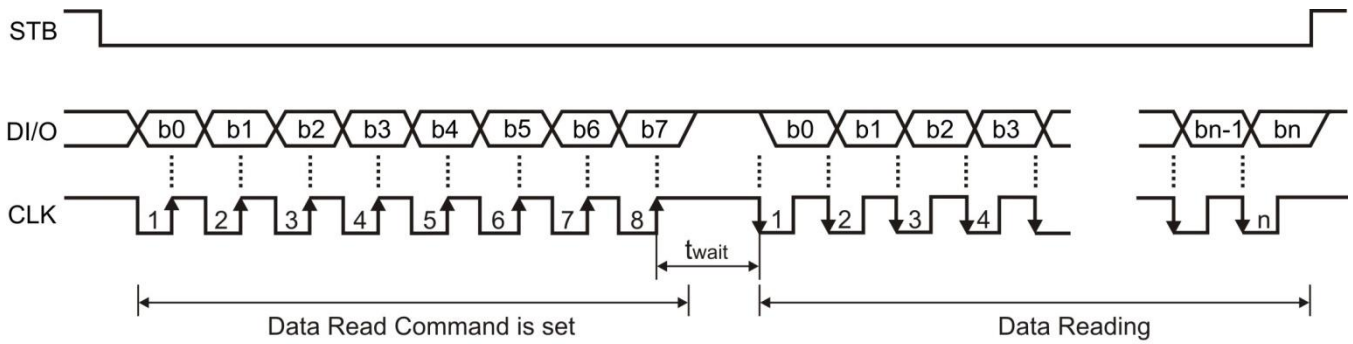
$$1 \text{ Frame} = T_{\text{display}} \times (n+1)$$

## SERIAL COMMUNICATION FORMAT

The following diagram shows the serial communication format.

### Reception (Data/Command Write)

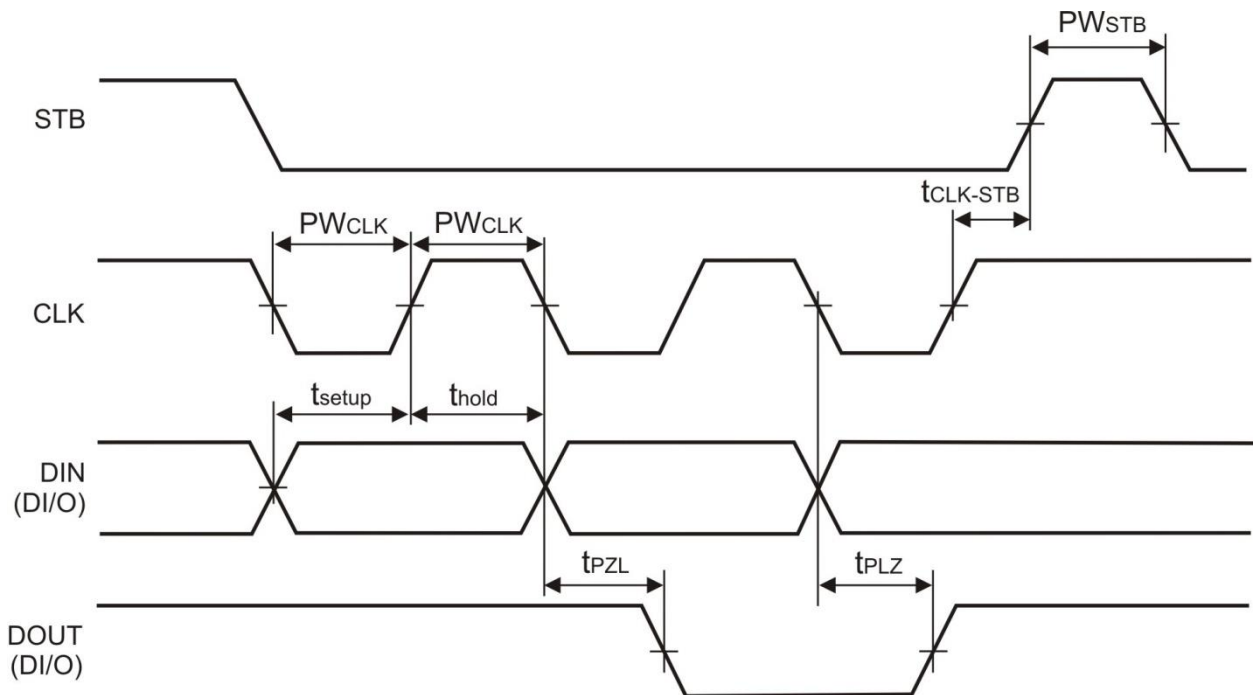


**Transmission (Data Read)**


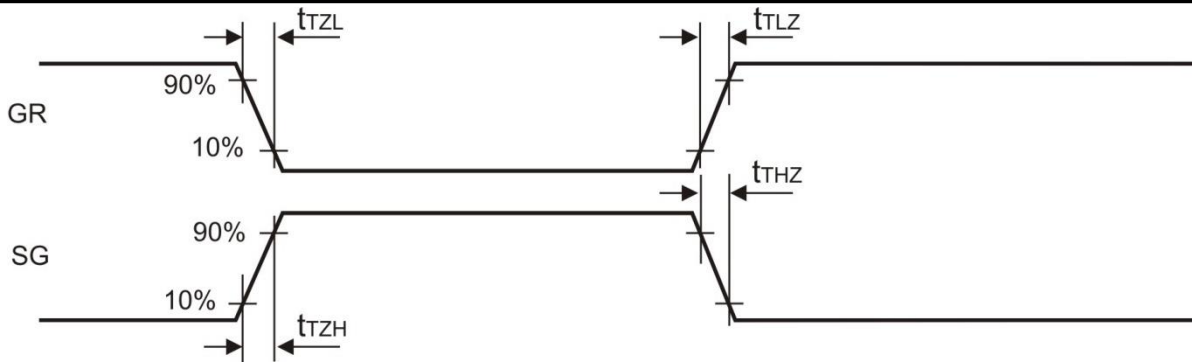
Where:  $t_{wait}$  (waiting time)  $\geq 1\mu s$

**SWITCHING CHARACTERISTIC WAVEFORM**

Switching Characteristics Waveform is given below.



$PW_{STB}$  (Strobe Pulse Width)  $\geq 1\mu s$   
 $t_{CLK-STB}$  (Clock - Strobe Time)  $\geq 1\mu s$   
 $PW_{CLK}$  (Clock Pulse Width)  $\geq 400ns$   
 $t_{setup}$  (Data Setup Time)  $\geq 100ns$   
 $t_{hold}$  (Data Hold Time)  $\geq 100ns$   
 $t_{PZL}$   
 $t_{PLZ}$



$$t_{TZL} < 1\mu s$$

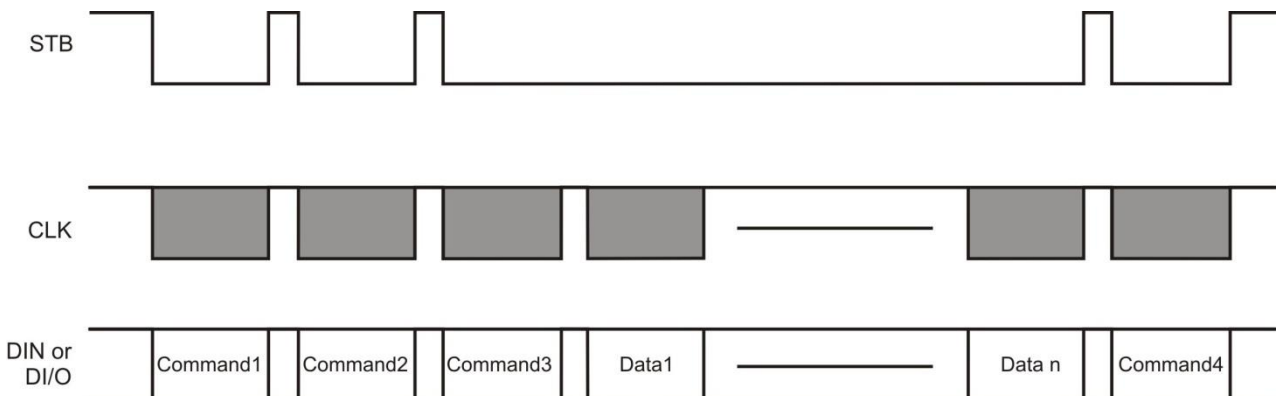
$$t_{TLZ} < 10\mu s$$

$$t_{TZH} \text{ (Rise Time)} \leq 1\mu s$$

$$t_{THZ} \text{ (Fall Time)} \leq 10\mu s$$

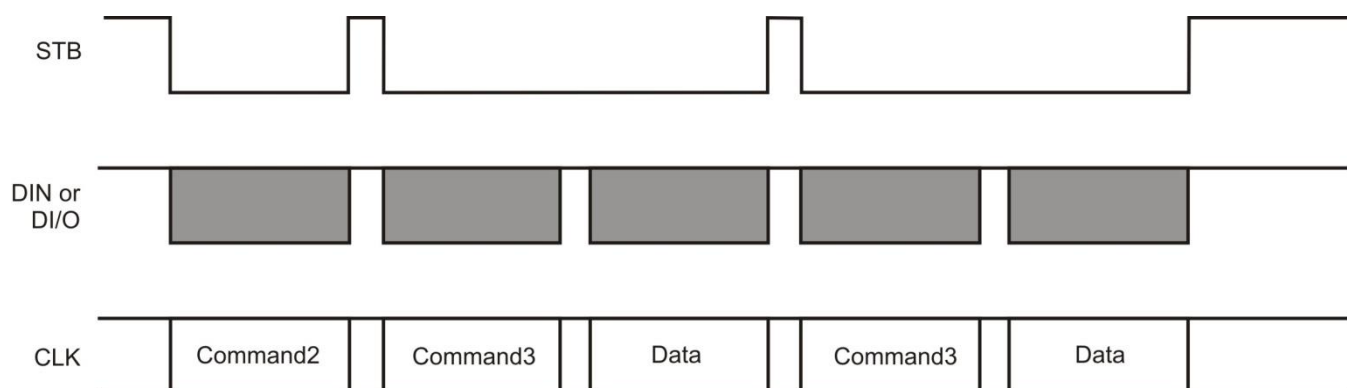
## APPLICATIONS

Display memory is updated by incrementing addresses. Please refer to the following diagram.

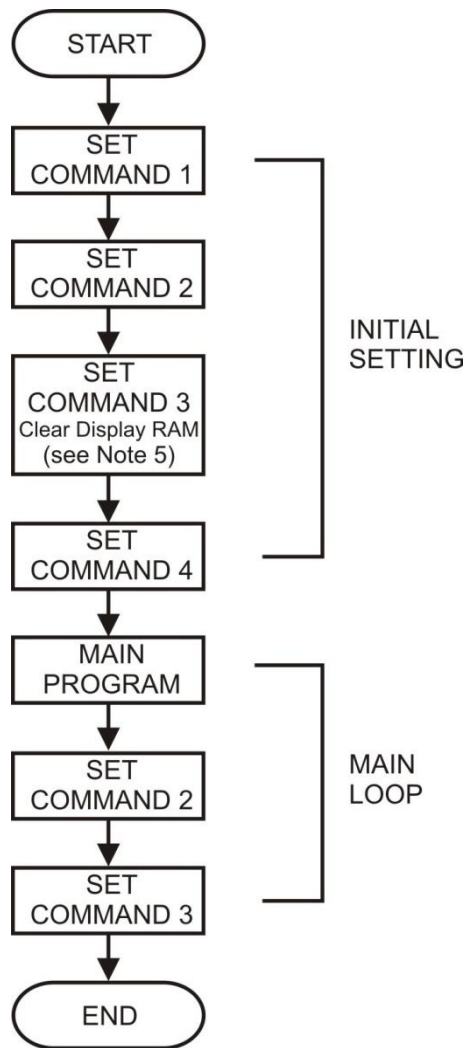


Where: Command 1: Display Mode Setting  
 Command 2: Data Setting Command  
 Command 3: Address Setting Command  
 Data 1 to Data n: Transfer Display Data (14 Bytes max)  
 Command 4: Display Control Command

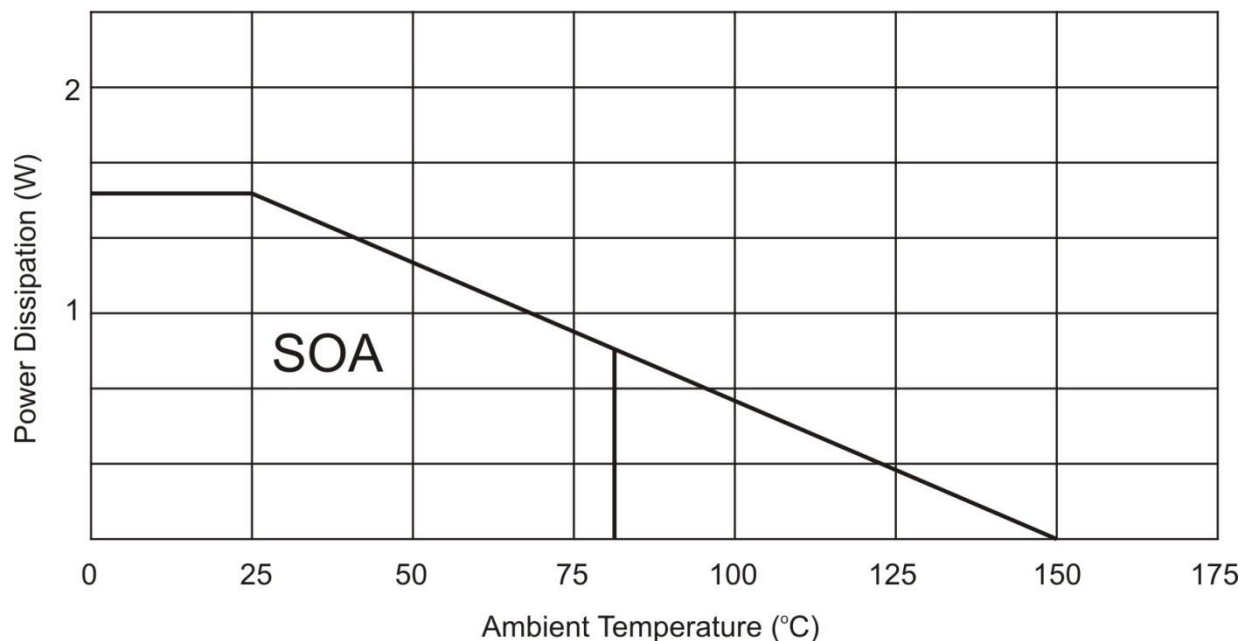
The following diagram shows the waveforms when updating specific addresses.



Where: Command 2 -- Data Setting Command  
 Command 3 -- Address Setting Command  
 Data -- Display Data

**RECOMMENDED SOFTWARE PROGRAMMING FLOWCHART**


- Notes:
1. Command 1: Display Mode Setting
  2. Command 2: Data Setting Commands
  3. Command 3: Address Setting Commands
  4. Command 4: Display Control Commands
  5. When IC power is applied for the first time, the contents of the Display RAM are not defined: thus, it is strongly suggested that the contents of the Display RAM must be cleared during the initial setting.

**POWER DISSIPATION CURVE**

**ABSOLUTE MAXIMUM RATINGS\***

(Unless otherwise stated, Ta=25°C, GND=0V)

Parameter	Symbol	Rating	Units
Supply Voltage	VCC	-0.5 to +4.2	V
Logic Input Voltage	V <sub>I</sub>	-0.5 to V <sub>DD</sub> +0.5	V
Driver Output Current/Pin	I <sub>OLGR</sub>	250	mA
	I <sub>OHSG</sub>	-18	mA
Maximum Driver Output Current/Total	I <sub>TOTAL</sub>	250	mA
Operation Temperature	T <sub>opr</sub>	-40 to +85	°C
Storage Temperature	T <sub>stg</sub>	-65 to +150	°C

\*Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**RECOMMENDED OPERATION RANGE**

(Unless otherwise stated, Ta= -40 to +85°C, GND=0V)

Parameter	Symbol	Min	Typ	Max	Unit
Logic Supply Voltage	$V_{DD}$	3.0	3.3	4.2	V
Dynamic Current (see Note)	$I_{DDdyn}$	.	.	1	mA
High-Level Input Voltage	$V_{IH}$	$0.7V_{DD}$	.	$V_{DD}$	V
Low-Level Input Voltage	$V_{IL}$	0	.	$0.3V_{DD}$	V

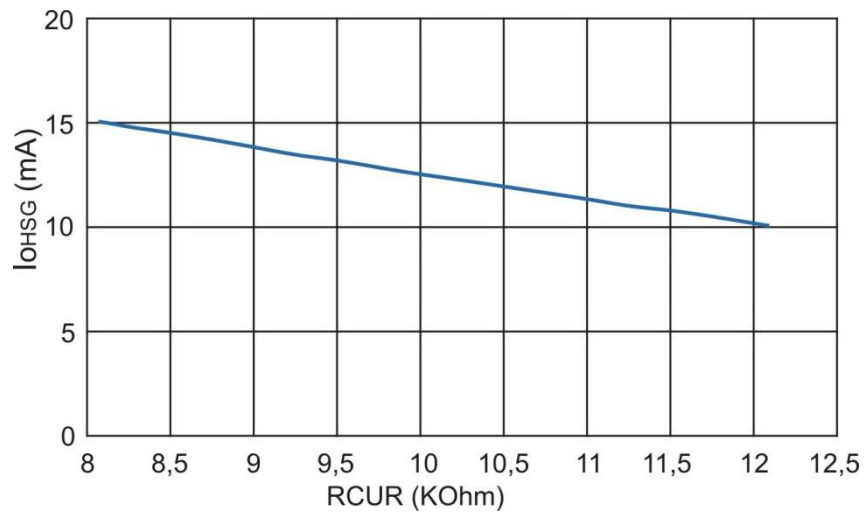
Note: Test Condition: Set Display Control Commands = 80H (Display Turn OFF State)

**ELECTRICAL CHARACTERISTICS**

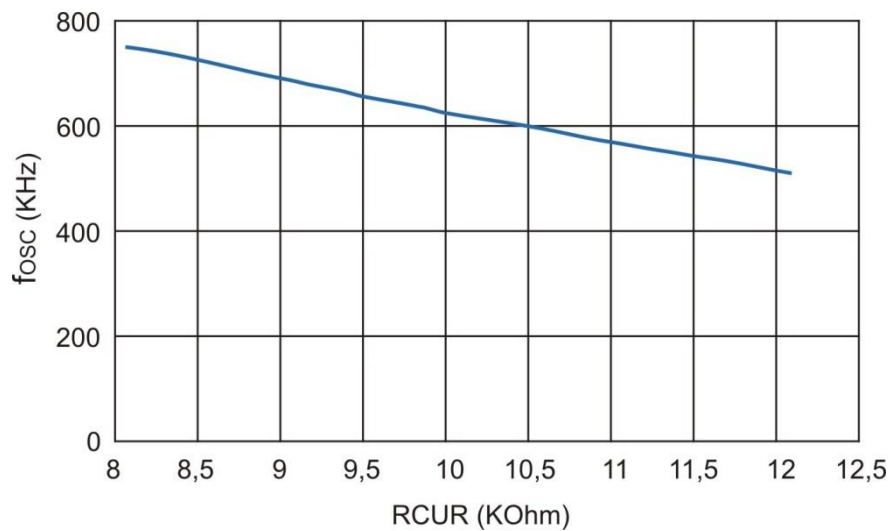
 (Unless otherwise stated,  $V_{DD} = 3.3$ , GND = 0V, Ta = -40 to 85°C)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
High-Level Output Current	$I_{OHSG1}$	$V_{DD} = 3.3$ , $V_{LED} = 2.3V$ R = 12.1KOhm SG1 to SG10 SG11/GR7 to SG13/GR5	8		10	mA
	$I_{OHSG2}$	$V_{DD} = 3.3V$ , $V_{LED} = 2.3V$ R = 8.07KOhm SG1 to SG10 SG11/GR7 to SG13/GR5	10		13	mA
Digital Input Current	$I_{DG}$	-	-0.2	-	+0.2	uA
Low-Level Digital Output Current	$I_{OLDG}$	$V_O = 0.4V$	4	-	-	mA
Segment High-Level Output Current Tolerance	$I_{TOLSG}$	$V_O = V_{DD} = 2.3V$ R = 12.1KOhm SG1 TO SG10 SG11/GR7 to SG13/GR5	-	-	±5	%
High-Level Input Voltage	$V_{IH}$	-	$0.7V_{DD}$	-	$0.3V_{DD}$	V
Low-Level Input Voltage	$V_{IL}$	-	-	-	$0.3V_{DD}$	V
Oscillation Frequency	$f_{OSC1}$	$V_{DD} = 3.3$ R = 12.1kOhm	400		500	kHz
K1, K2 Pull Down Resistor	$R_{PD}$	$V_{DD} = 5.0V$	40	-	100	KΩ

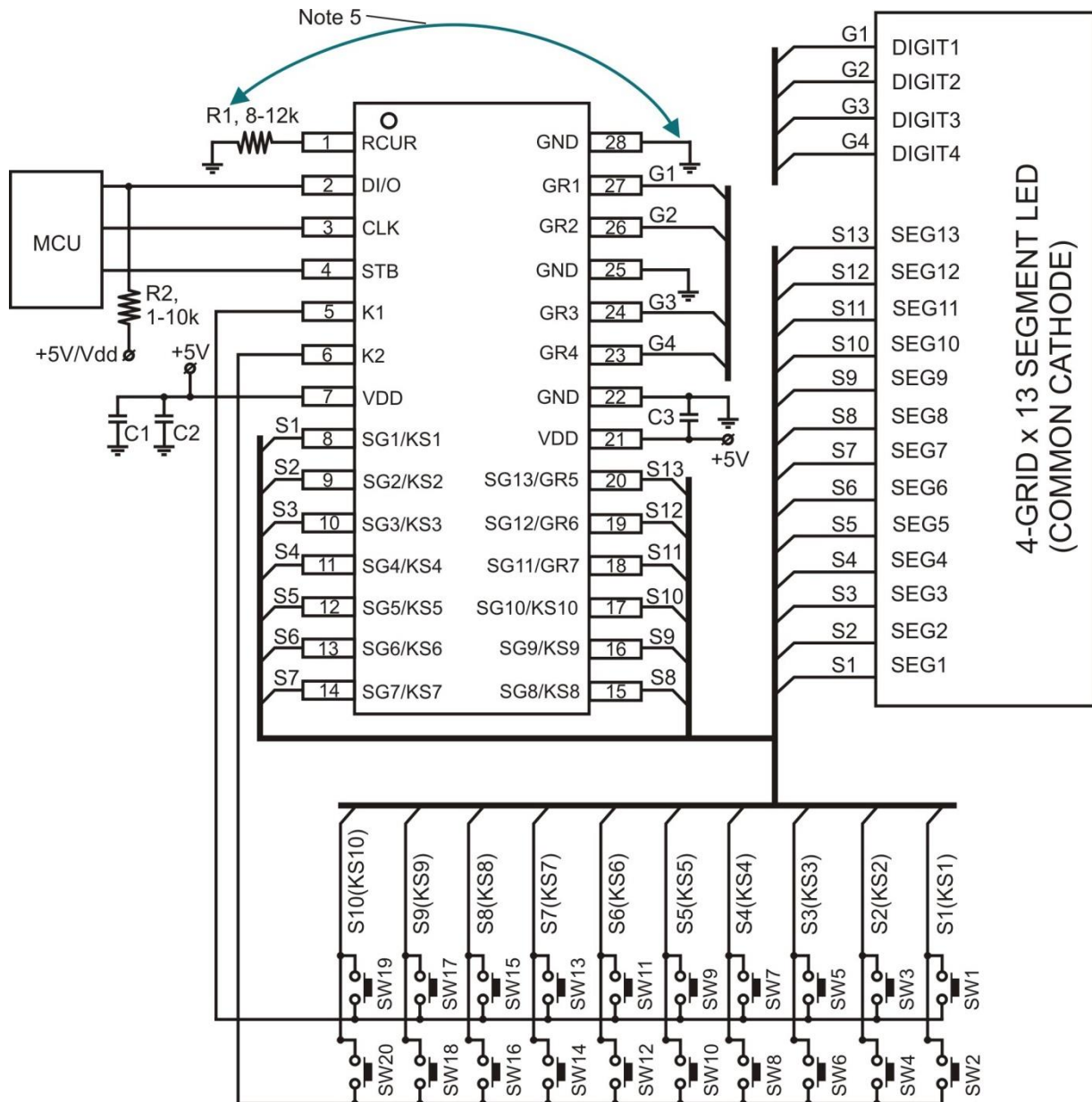
## High-Level Output Current



## Oscillation Frequency



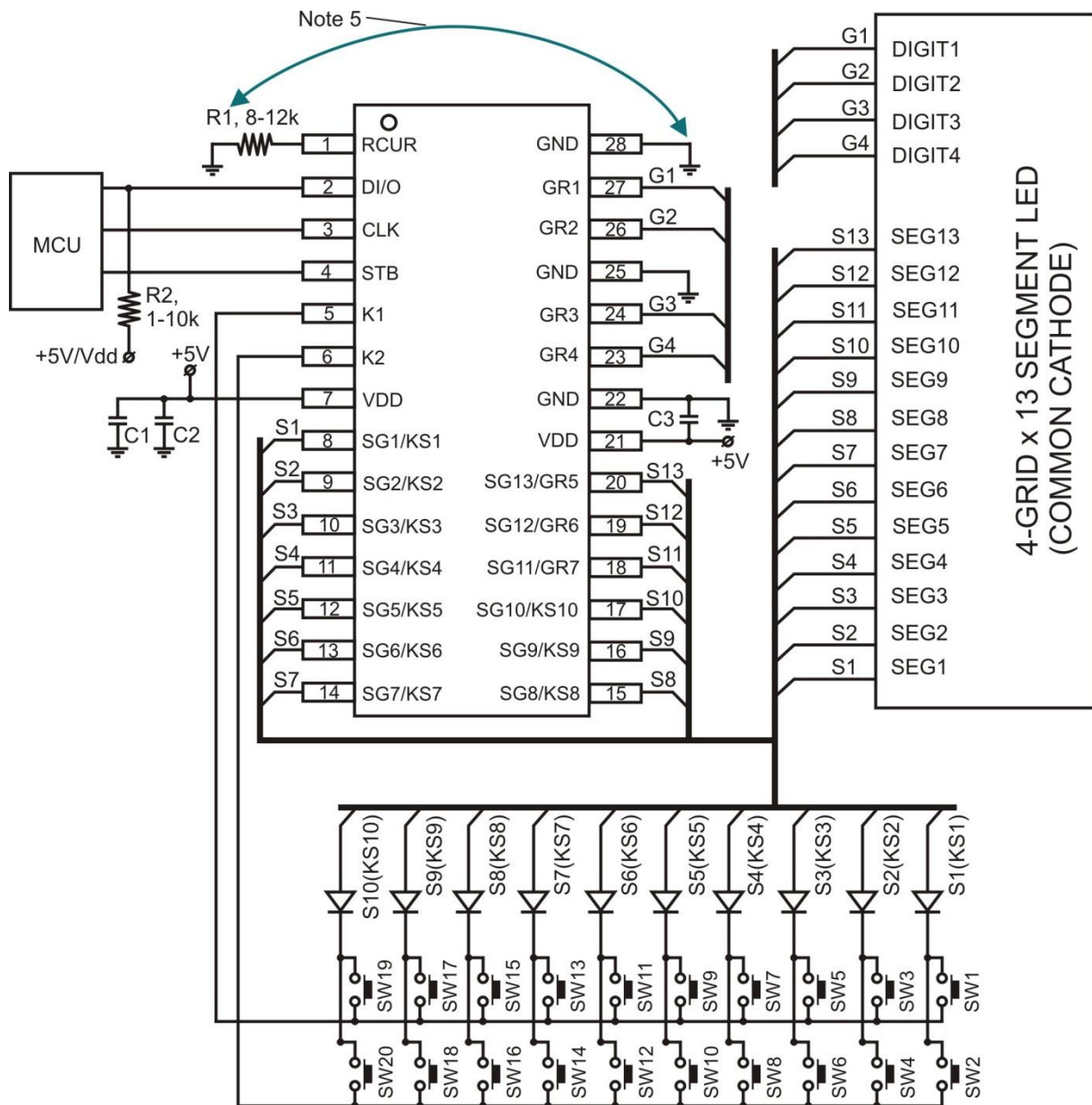
Remark: graphs are only  $V_{DD} = 5V$

**APPLICATION CIRCUIT**

**Note:**

1. Circuit is for V<sub>DD</sub> = 5V  
When V<sub>DD</sub> = 3.3V, Recommend R1 = 12.1kOhm.
2. The capacitors (0.1uF) connected between the GND and V<sub>DD</sub> Pins must be located as near as possible to the HT1628 chip.
3. HT1628 power supply is separate from the application system power supply.
4. For increase stability of IC and reduce noise, C1 & C2 should be placed closer to 7 pin and C3 should be placed closer to 21pin.
5. Ground of R1 should be routed directly to pin (28), not through common GND.

**Recommend value**

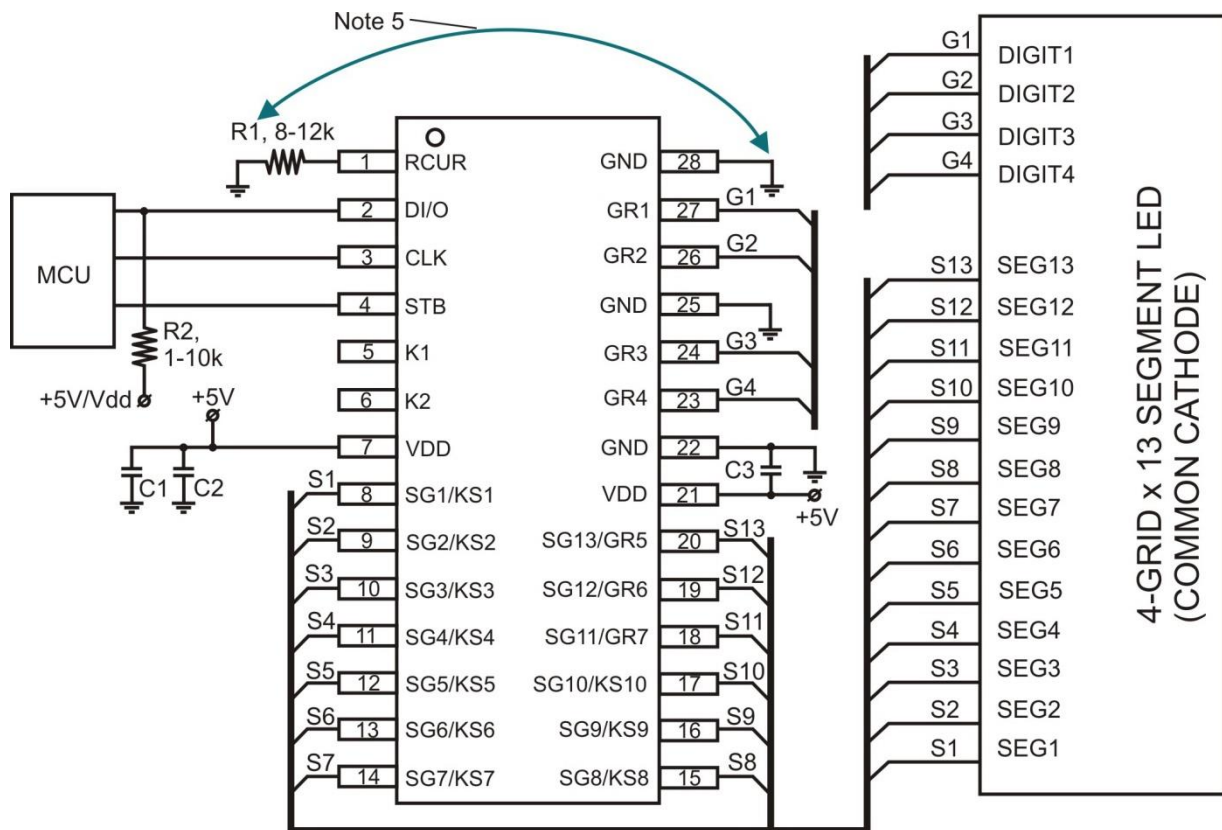
C1&C3 0.1uF-ceramics  
C2 470uF ~ 1000uF

**APPLICATION CIRCUIT (HT1628, key scan with diodes)**

**Note:**

1. When  $V_{DD} = 3.3V$ , Recommend  $R1 = 12.1k\Omega$
2. The capacitors (0.1uF) connected between the GND and  $V_{DD}$  Pins must be located as near as possible to the HT1628 chip.
3. HT1628 power supply is separate from the application system power supply
4. For increase stability of IC and reduce noise, C1 & C2 should be placed closer to 7 pin and C3 should be placed closer to 21pin.
5. Ground of R1 should be routed directly to pin (28), not through common GND.

**Recommend value**

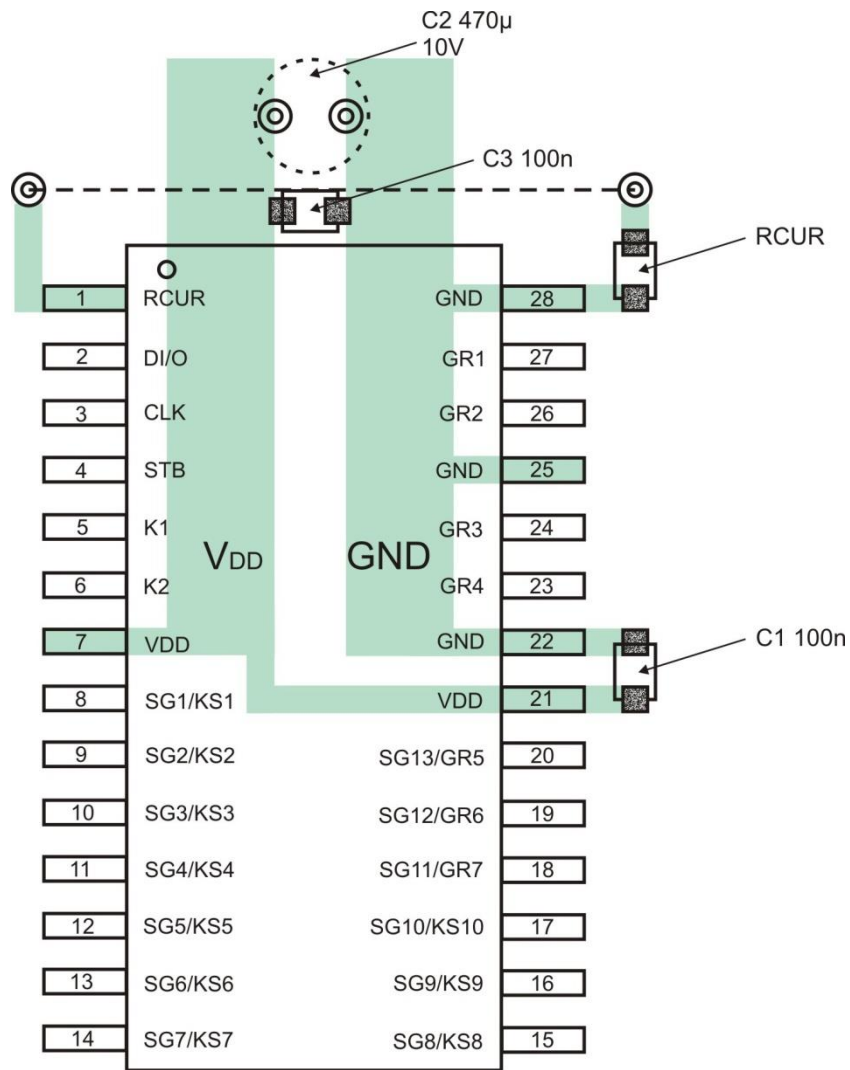
C1&C3 0.1uF - ceramics  
 C2 470uF ~ 1000uF

**APPLICATION CIRCUIT (HT1628 without key scan)**

**Note:**

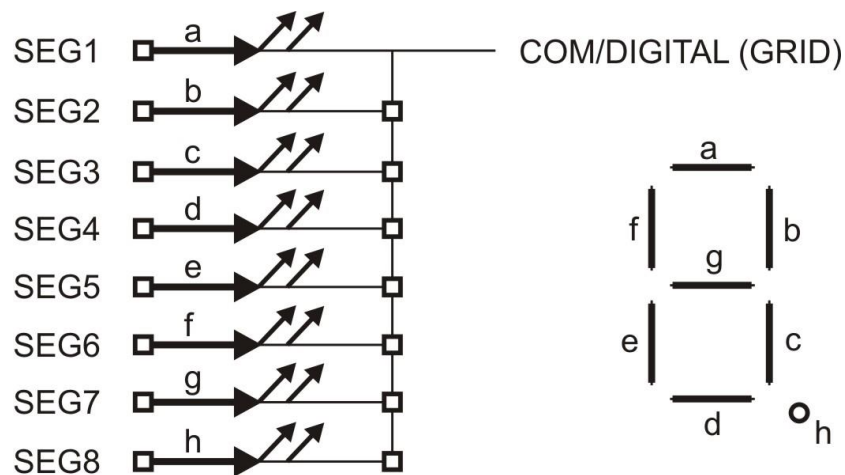
1. When  $V_{DD} = 3.3V$ , Recommend  $R1 = 12.1k\Omega$
2. The capacitors (0.1uF) connected between the GND and  $V_{DD}$  Pins must be located as near as possible to the HT1628 chip.
3. HT1628 power supply is separate from the application system power supply
4. For increase stability of IC and reduce noise, C1 & C2 should be placed closer to 7 pin and C3 should be placed closer to 21pin.
5. Ground of R1 should be routed directly to pin (28), not through common GND.

**Recommend value**

C1&C3 0.1uF-ceramics  
 C2 470uF ~ 1000uF

**Recommended Layout for GND and Vcc buses**


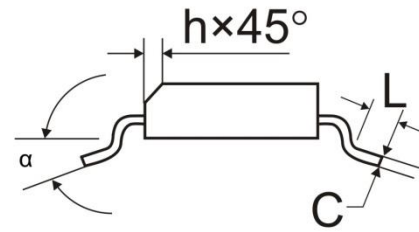
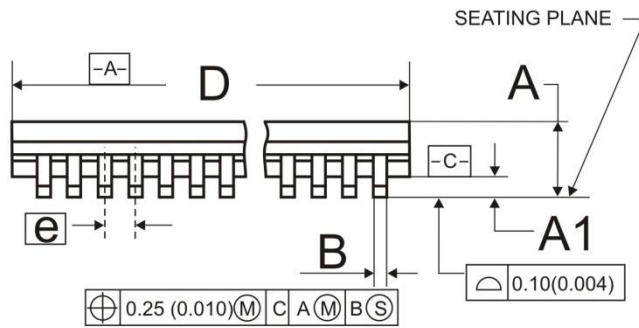
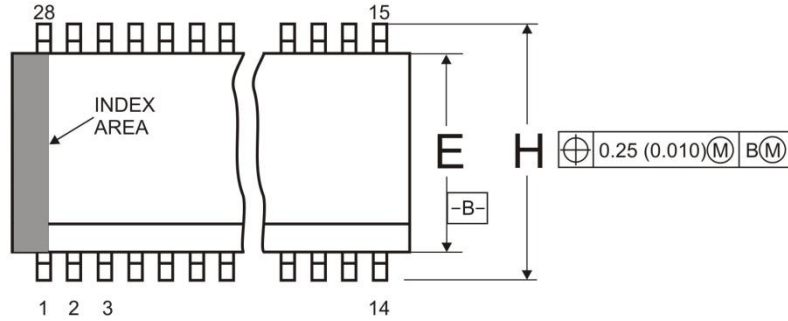
Layout considerations

**COMMON CATHODE TYPE LED PANEL**


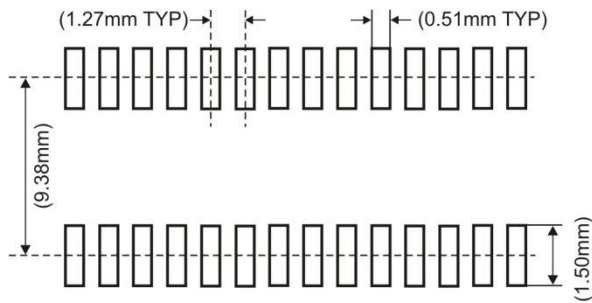
**PACKAGE DIMENSIONS**

**28SOP**

**Small Outline Plastic Packages (SOIC)**



**TYPICAL RECOMMENDED LAND PATTERN**



Symbol	Min	Max	Notes
A	2.35	2.65	-
A1	0.10	0.30	-
B	0.33	0.51	9
C	0.23	0.32	-
D	17.70	18.10	3
E	7.40	7.60	4
e	1.27 BSC		-
H	10.00	10.65	-
h	0.25	0.75	5
L	0.40	1.27	6
N	28		7
$\alpha$	0°	8°	-

**NOTES:**

1. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
4. Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
6. "L" is the length of terminal for soldering to a substrate.
7. "N" is the number of terminal positions.
8. Terminal numbers are shown for reference only.
9. The lead width "B", as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch)
10. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.